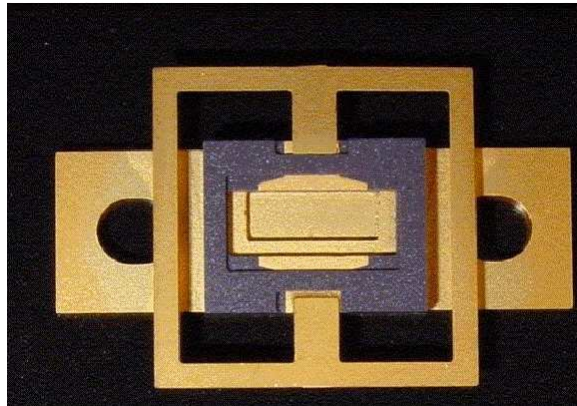




Description

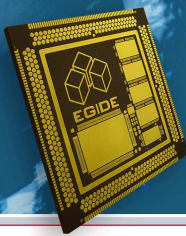
Egide's knowledge in RF design, its in-house ceramics technology and state-of-the-art assembly processes benefit the company's range of hermetic packages for GaAs, GaN or SiC RF Power applications. Available as standard product or customized design, they are compliant with the demanding requirements for hermeticity, increase in frequency and thermal management associated with avionics, military and communications markets.



Features

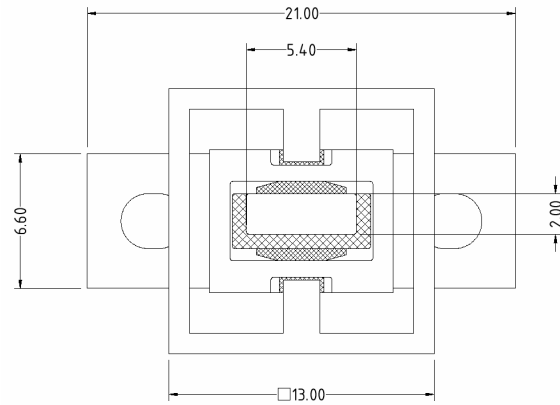
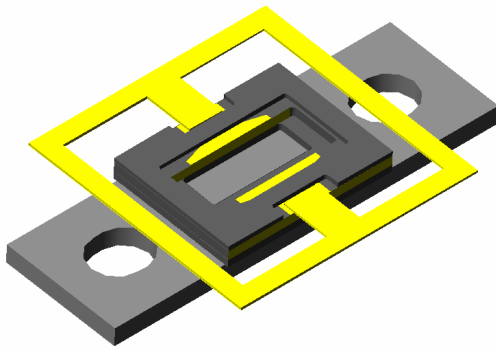
- Wide bandwidth capability (>10GHz)
- Hermetic design with flange
- Multilayer HTCC feedthru (Al_2O_3)
- CuW or CuMo base for high thermal dissipation
- Compatible with AuSn brazing
- No BeO
- Direct die attach to the heatsink for enhanced power handling capability

Contact : sales@egide.fr – sales@egideusa.com
www.egideusa.com - www.egide.fr



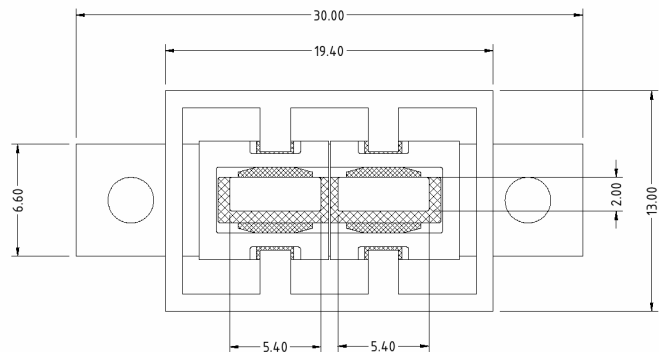
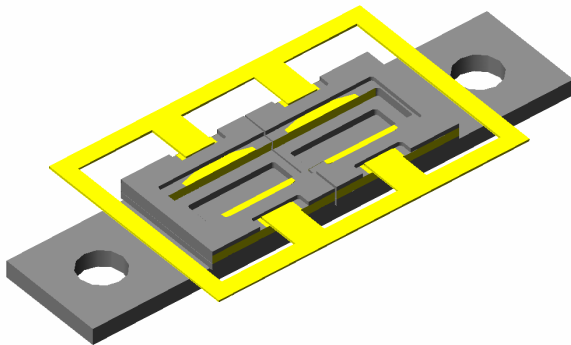
Package outline (examples)

Single amplifier design



Dimensions in mm

Push pull design



Dimensions in mm